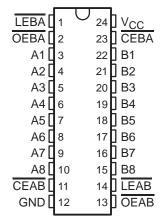
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Support Live Insertion
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Ceramic (JT) DIPs

description

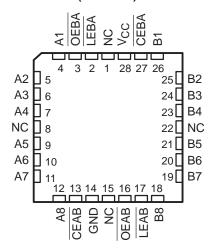
These octal transceivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The 'LVT543 contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

SN54LVT543 . . . JT PACKAGE SN74LVT543 . . . DB, DW, OR PW PACKAGE (TOP VIEW)



SN54LVT543 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The A-to-B enable (CEAB) input must be low in order to enter data from A or to output data from B. If CEAB is low and LEAB is low, the A-to-B latches are transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the CEBA, LEBA, and OEBA inputs.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.



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description (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT543 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

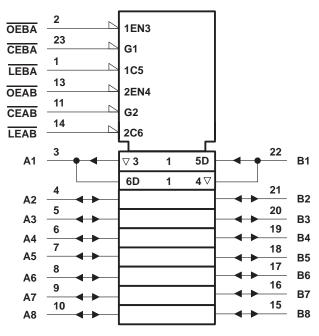
The SN54LVT543 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVT543 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE†

	OUTPUT			
CEAB	LEAB	OEAB	Α	В
Н	Χ	Х	Χ	Z
Х	Χ	Н	Χ	Z
L	Н	L	Χ	в ₀ ‡
L	L	L	L	L
L	L	L	Н	Н

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

logic symbol§

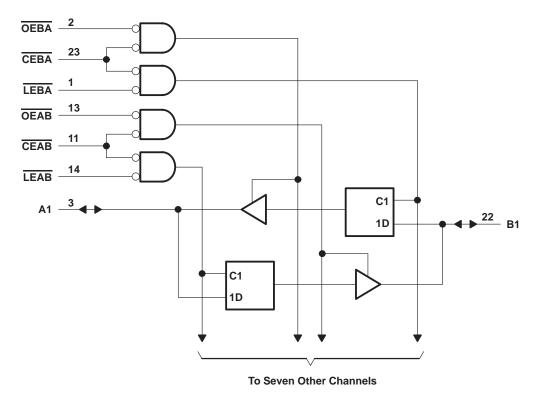


§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, and PW packages.



[‡] Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, and PW packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} –0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)
Voltage range applied to any output in the high state or power-off state, V _O (see Note 1) −0.5 V to 7 V
Current into any output in the low state, IO: SN54LVT543
SN74LVT543 128 mA
Current into any output in the high state, I _O (see Note 2): SN54LVT543
SN74LVT543 64 mA
Input clamp current, I_{IK} ($V_I < 0$)
Output clamp current, I_{OK} ($V_O < 0$)
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DB package
DW package 1.7 W
PW package 0.7 W
Storage temperature range, T _{sto} –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.



SN54LVT543, SN74LVT543 3.3-V ABT OCTAL REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 4)

			SN54L	VT543	SN74L	/T543	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	F	2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage		,<	5.5		5.5	V
IOH	High-level output current		(5)	-24		-32	mA
lOL	Low-level output current		Pac	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	8	10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS				154LVT54	13	SN	174LVT54	4 3	UNIT	
PARAMETER	1	EST CONDITIONS		MIN	TYP [†]	MAX	MIN	TYP†	MAX	UNII	
VIK	$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA				-1.2			-1.2	V	
	$V_{CC} = MIN \text{ to } MAX^{\ddagger},$	I_{CC} = MIN to MAX [‡] , I_{OH} = -100 μA					VCC-C).2			
\/a	$V_{CC} = 2.7 \text{ V},$						2.4			V	
VOH	V _{CC} = 3 V	$I_{OH} = -24 \text{ mA}$		2						V	
	VCC = 3 V	$I_{OH} = -32 \text{ mA}$					2				
	V _{CC} = 2.7 V	I _{OL} = 100 μA				0.2			0.2		
	VCC = 2.7 V	I _{OL} = 24 mA				0.5			0.5		
V _{OL}		I _{OL} = 16 mA				0.4			0.4	V	
VOL	V _{CC} = 3 V	$I_{OL} = 32 \text{ mA}$				0.5			0.5	V	
	VCC = 3 V	I _{OL} = 48 mA				0.55					
		I _{OL} = 64 mA				2			0.55		
	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND	Control		3	±1			±1		
	$V_{CC} = 0$ or MAX ‡ ,	V _I = 5.5 V	inputs		24	10			10		
lį	V _{CC} = 3.6 V	V _I = 5.5 V			7	20			20	μΑ	
		$\Lambda^{I} = \Lambda^{CC}$	A or B ports§		2	5			5		
		V _I = 0			5	-10			-10		
l _{off}	$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V		2					±100	μΑ	
lia i s	V _{CC} = 3 V	V _I = 0.8 V	A or B ports	75			75			μΑ	
l(hold)	VCC = 3 V	V _I = 2 V	A or B ports	-75			-75			μΑ	
lozh	$V_{CC} = 3.6 \text{ V},$	V _O = 3 V				1			1	μΑ	
lozL	$V_{CC} = 3.6 \text{ V},$	V _O = 0.5 V				-1			-1	μΑ	
			Outputs high		0.13	0.19		0.13	0.19		
lcc	$V_{CC} = 3.6 \text{ V},$	$I_{O} = 0$,	Outputs low		8.8	12		8.8	12	mA	
icc	$V_I = V_{CC}$ or GND Outputs disabled				0.13	0.19		0.13	0.19	111/4	
ΔI _{CC} ¶	V_{CC} = 3 V to 3.6 V, One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND					0.2			0.2	mA	
C _i	V _I = 3 V or 0				4.5			4.5		pF	
C _{io}	V _O = 3 V or 0				11			11		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. ‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $[\]$ Unused terminals at VCC or GND

 $[\]P$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54LVT543, SN74LVT543 3.3-V ABT OCTAL REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

					SN54LVT543				SN74LVT543			
				V _{CC} =		VCC =	2.7 V	V _{CC} =		VCC =	2.7 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _W	Pulse duration,	LEAB or LEBA low	3.3		3.3		3.3		3.3		ns	
		A or B before LEAB or LEBA↑ A or B before CEAB or	Data high	0		0		0		0		
 .	Satura timo		Data low	0.8		1.1		0.8		1.1		ns
'su	t _{SU} Setup time		Data high	0	É	0		0		0		115
		CEBA↑	Data low	0.9	20	1.2		0.9		1.2		
ļ.,	t _h Hold time	A or B after CEAB or CEBA↑ A or B after CEAB or CEBA↑		1.7	0	1.7		1.7		1.7		ne
۱'n				1.8	Q	1.8		1.8		1.8		ns

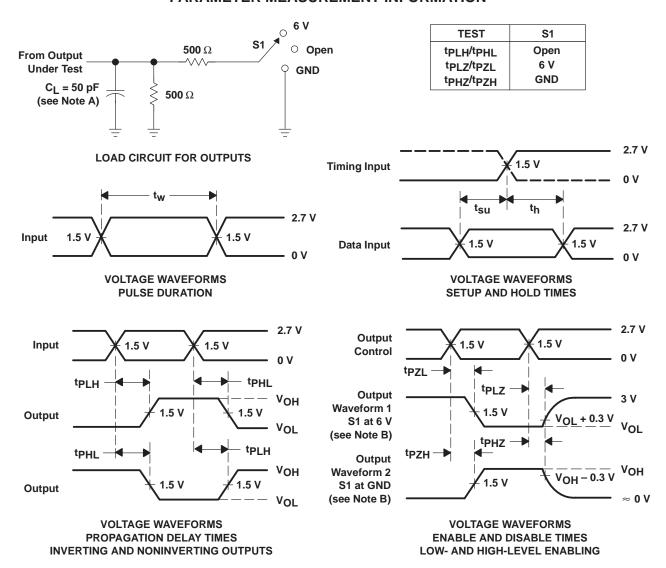
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN54L	VT543			SN	74LVT5	43		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		V	V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP [†]	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	1	4.9		5.7	1	2.9	4.7		5.5	ns
^t PHL	AOIB	BOIA	1	4.8		6	1	3.3	4.6		5.8	115
^t PLH	<u>LE</u>	A or B	1	6.1	13)	7.5	1	4	5.9		7.3	ns
^t PHL	LE	AOIB	1	5.9	13/	7.5	1	4.1	5.7		7.3	115
^t PZH	ŌĒ	A or B	1	6	10	7.8	1	4.1	5.8		7.6	ns
t _{PZL}	OE	AOIB	1.1	6.6		8.4	1.1	4.5	6.4		8.2	115
^t PHZ	ŌĒ	A or B	2.4	6.7		7.3	2.4	4.8	6.5		7.1	ns
t _{PLZ}	OE	AOIB	2	6		6.1	2	4	5.8		5.9	115
^t PZH	CE	A or B	1	6.2		7.8	1	4.2	6		7.6	ns
^t PZL	CE	AOLR	1.4	6.9		8.5	1.4	4.7	6.7		8.3	115
^t PHZ	CE	A or B	2.3	6.6		7.3	2.3	4.7	6.4		7.1	ns
t _{PLZ}	OL .	AUIB	2	5.6		5.8	2	3.8	5.4		5.6	115

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq$ 2.5 ns. $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74LVT543DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT543
SN74LVT543DW.B	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT543

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

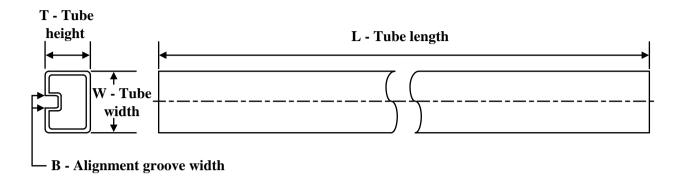
⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE

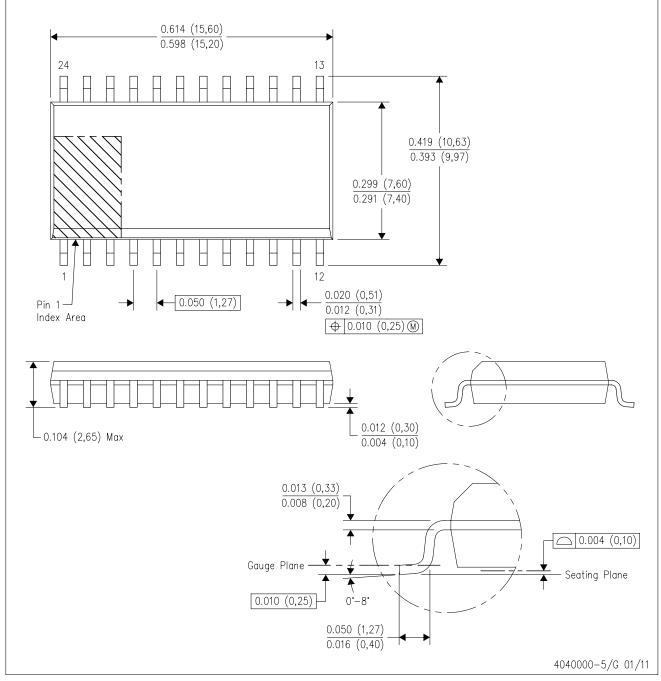


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LVT543DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74LVT543DW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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Last updated 10/2025